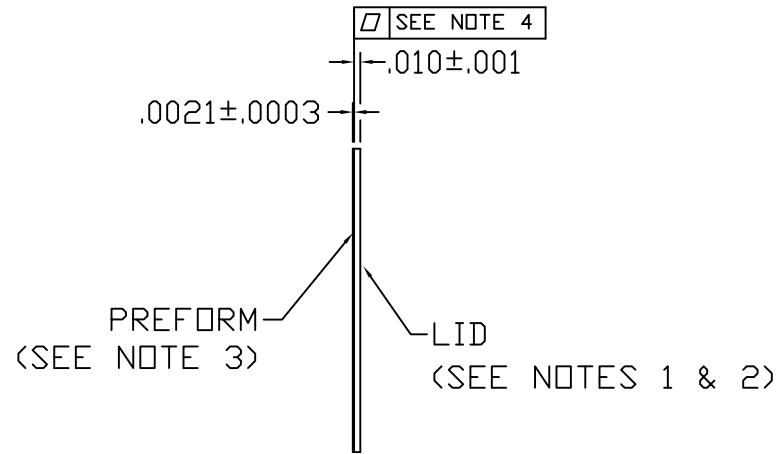
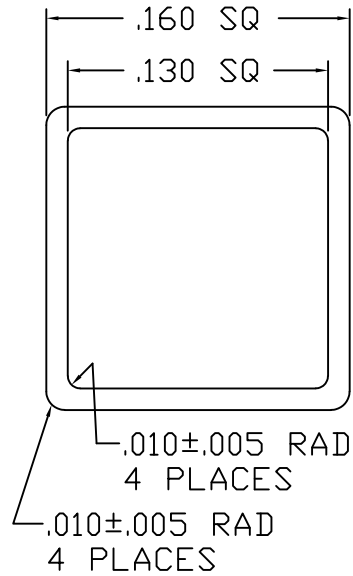


SSM P/N CL-16007



NOTES

1. MAT'L : KOVAR OR ALLOY 42
2. PLATING : 1st LAYER 50/350 MICROINCHES NI
 2nd LAYER 25 MICROINCHES MIN Au
 3rd LAYER 50/350 MICROINCHES NI
 4th LAYER 25 MICROINCHES MIN Au
- NOTES : TOTAL NICKEL LAYERS SHALL NOT EXCEED 450 MICROINCHES AND THE SUM OF BOTH GOLD LAYERS SHALL BE 50 MICROINCHES MINIMUM.
3. PREFORM - 80% ±1% Au
 20% Sn
4. FLATNESS : ONE MIL (.001) MAXIMUM PER 1/2" T.I.R
5. TOLERANCES TO BE (XX) 3 PLACES ±.002 UNLESS OTHERWISE NOTED

Part Name: CL-16007		Description: Hi-Rel Combo Lid	
P/n: 160130-010-0021-4		Mfg: Coining	Scale 4 = 1
Spectrum Semiconductor Materials, Inc. 155 Nicholson Lane San Jose, CA 95134 PH: (408) 435-5555 FX: (408)435-8226			

